Microsemi.

Software Release and Errata Notice

ZL880SLVVP VeriVoice Professional Software P1.3.0

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This document describes new features and corrected errata for the ZL880SLVVP VeriVoiceTM Professional Software. Refer to the Line Test API User's Guide (Document ID #081470), Rev 22 for more details.

1.0 REVISION SUMMARY

This is a bug fix and feature addition to revision P1.2.0 of the ZL880SLVVP software. *This release replaces all previous release.*

This release provides a complete set of the available VeriVoice Professional tests as described in Table 2-2 of the LT-API User's Guide.

PLEASE READ THE FOLLOWING CAREFULLY

This release is compatible with the following VP-API-II release packages:

- LE71HRSK0002 P2.22.0 and P2.23.0
- LE71SDKAPIL P2.22.0 and P2.23.0

This release supports all current versions of miSLIC silicon, which includes the following:

- ZL88801 Shared Buck-Boost ABS Supply
- Le9662 Shared Buck-Boost ABS Supply
- Le9672 Tracking
- Le9661 Single Channel Tracking

2.0 SOURCE FILES

The release package has the following file/folder structure:

- \ReadMe.txt High level installation instructions.
- \api lib\vp886 api ZL880 VP-API-II extension source files (primitives).
- \api lib\vp886 api\vp886 gain toolbox.c new VP-API-II extension
- \lt_api\common LT-API interface implementation files.
- \lt_api\documents LT-API User's Guide and this document.
- \lt api\includes LT-API interface definition source files.
- \lt api\vp886 lt LT-API interface definition source files.

Details pertaining to the source files can be found in the LT-API User's Guide section 1.3.

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3.0 CORRECTED ERRATA FROM P1.2.0

C1 None

4.0 ADDITIONS / FEATURES

- C2 Including support for new Microsemi device Le9661.
- Reduced the Resistive Faults Test (LT_TID_RES_FLT) duration in the presence of an AC foreign voltage.
- Auto-disable the VP-API-II DTMF detection feature added in API P2.23.0 for the duration of a test if DTMF detection is enabled. This is necessary because the DTMF detector and line tests share device resources.

5.0 OPERATIONAL NOTES

- N1 Operational Note: If a VP-API-II thermal fault event (VP_LINE_EVID_THERM_FLT) is generated during a line test, the test will continue to run normally; however, the results of the test are invalid. This is operationally different than the LE880SLVVP and LE880SLVV VeriVoice packages in that these packages will start the LT-API abort routine and return LT_xyz_NOT_MEASURED for all result arguments. Therefore, applications that receive a VP_LINE_EVID_THERM_FLT during a line test should ignore the result arguments generated by the ZL880SLVVP test.
- **N2 Operational Note:** All LT-API tests will stop the VP-API Ground Fault Protection feature (VP_OPTION_ID_GND_FLT_PROTECTION) from monitoring for a ground fault condition to clear. If the Ground Fault Protection feature changes the line to VP_LINE_DISCONNECT prior to running a line test, the application is responsible for configuring the line state after the test completes.
- N3 Operational Note: All LT-API tests will report ItStatus LT_STATUS_ERROR_VP_TEST if the current VP-API line state is VP_LINE_RINGING or VP_LINE_RINGING_POLREV when the VP-API Adaptive Ringing feature (VP_DEVICE_OPTION_ID_ADAPTIVE_RINGING) is enabled.
- **N4 Operational Note:** Applications must wait 100ms after calling VpSetLineState() to call LtStartTest() under the following conditions:
 - From a ringing state to a non ringing state.
 - From normal polarity to reverse polarity.
 - From reverse polarity to normal polarity.
 - From VP_LINE_TIP_OPEN to VP_LINE_ACTIVE with a ground key present.



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